



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

1752  
OIPB  
12/9/02

In re application of : Confirmation No. 4175  
Hideo HADA et al. : Docket No. 2001-1787A  
Serial No. 09/996,676 : Group Art Unit 1752  
Filed November 30, 2001 : Examiner R. Ashton

**POSITIVE-WORKING  
PHOTORESIST COMPOSITION**

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1C 1100 MAIL ROOM  
THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

**SUPPLEMENTAL RESPONSE**

Assistant Commissioner for Patents,  
Washington, D.C. 20231

Sir:

Further to the response filed on November 18, 2002, please further amend the present application as follows:

**IN THE CLAIMS:**

**Please amend claim 12 as follows:**

12. (Amended) A positive-working photoresist composition which comprises, as a uniform solution in an organic solvent:

(A) 100 parts by weight of a resinous compound capable of being imparted with increased solubility in an aqueous alkaline solution by interaction with an acid;

(B) from 0.5 to 30 parts by weight of a radiation-sensitive acid generating compound capable of generating an acid by irradiation with a radiation; and

(C) an organic solvent in an amount sufficient to dissolve the components (A) and (B), the component (A) being a copolymer consisting of the monomeric units of

(a1) from 30 to 60% by moles of 2-alkyl-2-adamantyl (meth) acrylate units having the formula: